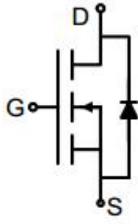
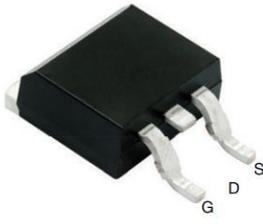


## N-Channel Enhancement Mode Power MOSFET

<p><b>Description</b></p> <p>The GT100N12M uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>• <math>V_{DS}</math> 120V</li> <li>• <math>I_D</math> (at <math>V_{GS} = 10V</math>) 70A</li> <li>• <math>R_{DS(ON)}</math> (at <math>V_{GS} = 10V</math>) &lt; 10m<math>\Omega</math></li> <li>• 100% Avalanche Tested</li> <li>• RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>• Power switch</li> <li>• DC/DC converters</li> </ul>	 <p>Schematic diagram</p>  <p>TO-263</p>
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### Ordering Information

Device	Package	Marking	Packaging
GT100N12M	TO-263	GT100N12	800pcs/Reel

### Absolute Maximum Ratings $T_C = 25^\circ C$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	120	V
Continuous Drain Current	$I_D$	$T_C = 25^\circ C$	70
		$T_C = 100^\circ C$	44
Pulsed Drain Current (note1)	$I_{DM}$	280	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D$	100	W
Single pulse avalanche energy (note2)	$E_{AS}$	156	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 150	$^\circ C$

### Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{thJA}$	50	$^\circ C/W$
Maximum Junction-to-Case	$R_{thJC}$	1.25	$^\circ C/W$

Specifications $T_J = 25^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	120	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 120V, V_{GS} = 0V$	--	--	1	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	3.0	4.0	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	--	7.4	10	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{GS} = 5V, I_D = 20A$	--	25	--	S
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 60V,$ $f = 1.0\text{MHz}$	--	2990	--	pF
Output Capacitance	$C_{oss}$		--	335	--	
Reverse Transfer Capacitance	$C_{rss}$		--	4	--	
Total Gate Charge	$Q_g$	$V_{DD} = 60V,$ $I_D = 20A,$ $V_{GS} = 10V$	--	45	--	nC
Gate-Source Charge	$Q_{gs}$		--	16	--	
Gate-Drain Charge	$Q_{gd}$		--	11	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 60V,$ $I_D = 20A,$ $R_G = 1.6\Omega$	--	15	--	ns
Turn-on Rise Time	$t_r$		--	10	--	
Turn-off Delay Time	$t_{d(off)}$		--	34	--	
Turn-off Fall Time	$t_f$		--	8	--	
<b>Drain-Source Body Diode Characteristics</b>						
Continuous Body Diode Current	$I_S$	$T_C = 25^\circ\text{C}$	--	--	70	A
Body Diode Voltage	$V_{SD}$	$T_J = 25^\circ\text{C}, I_{SD} = 20A, V_{GS} = 0V$	--	--	1.2	V
Reverse Recovery Charge	$Q_{rr}$	$I_F = 20A, V_{GS} = 0V$ $di/dt = 100A/\mu s$	--	106	--	nC
Reverse Recovery Time	$T_{rr}$		--	60	--	ns

### Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition :  $T_J = 25^\circ\text{C}, V_{DD} = 50V, V_{GS} = 10V, L = 0.5\text{mH}, R_G = 25\Omega$

The table shows the minimum avalanche energy, which is 420mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

### Gate Charge Test Circuit



### Switch Time Test Circuit

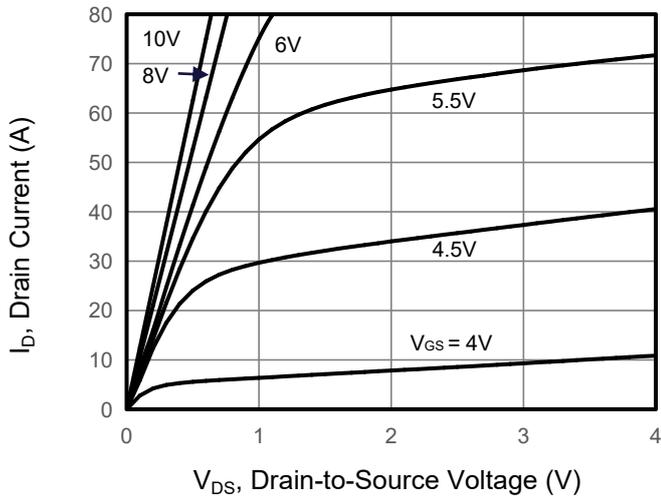


### EAS Test Circuit

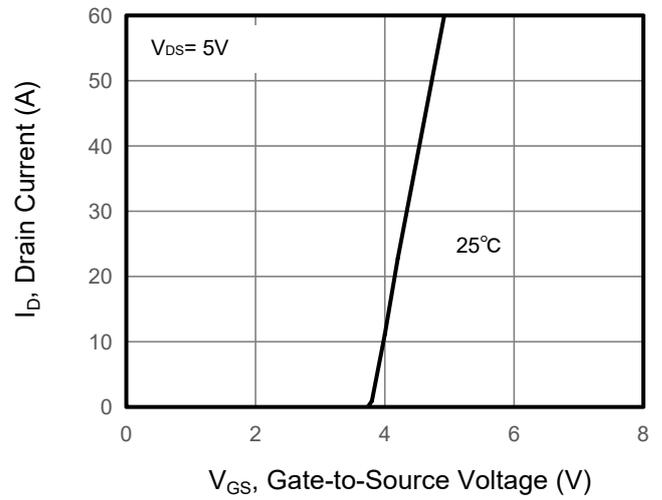


Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

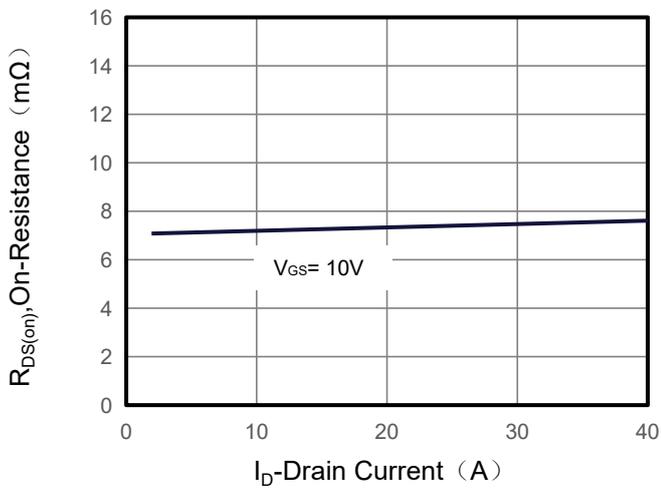
**Figure 1. Output Characteristics**



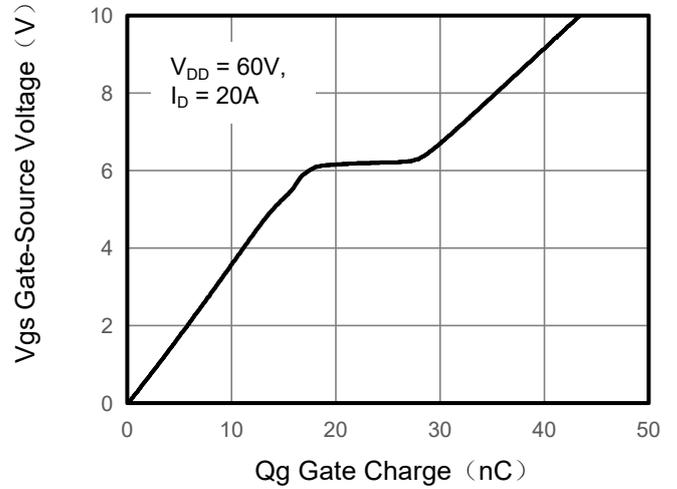
**Figure 2. Transfer Characteristics**



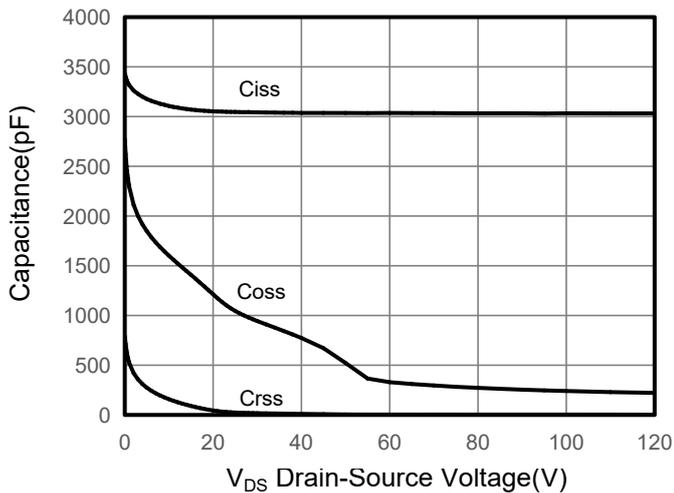
**Figure 3. Drain Source On Resistance**



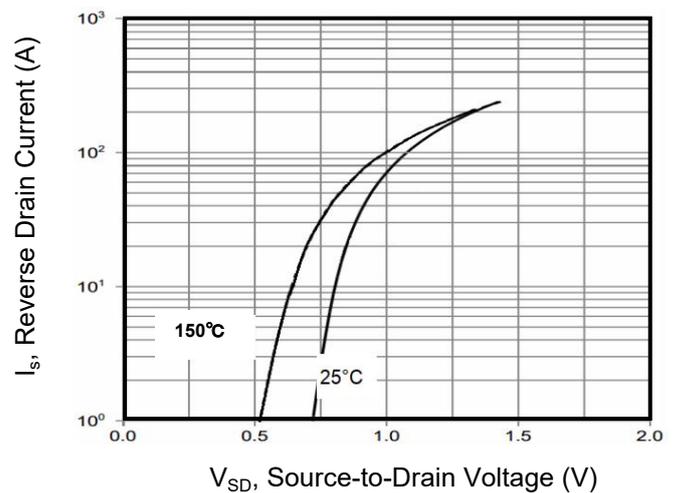
**Figure 4. Gate Charge**



**Figure 5. Capacitance**

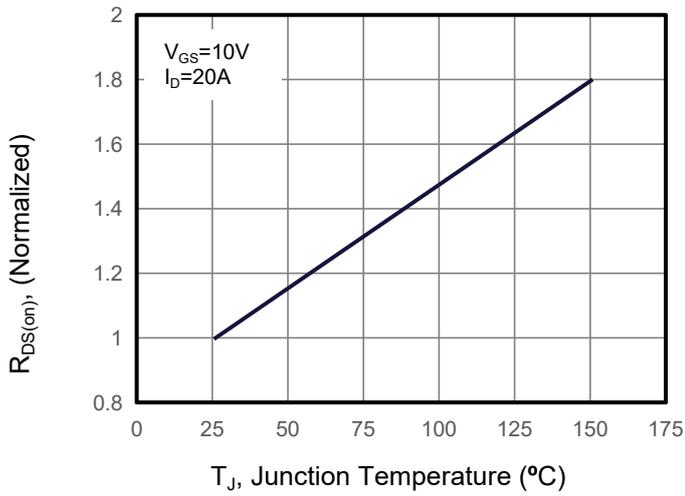


**Figure 6. Source-Drain Diode Forward**

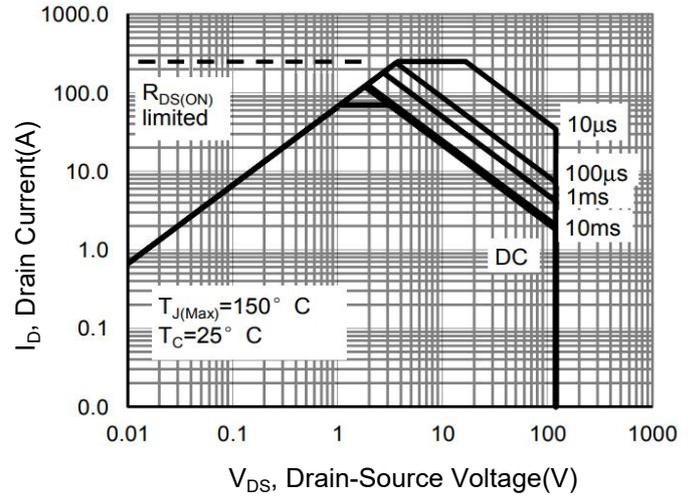


## Typical Characteristics $T_J = 25^\circ\text{C}$ , unless otherwise noted

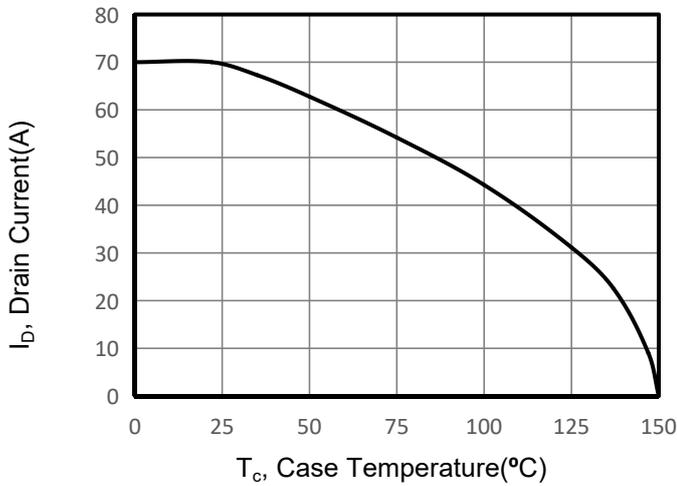
**Figure 7. Drain-Source On-Resistance**



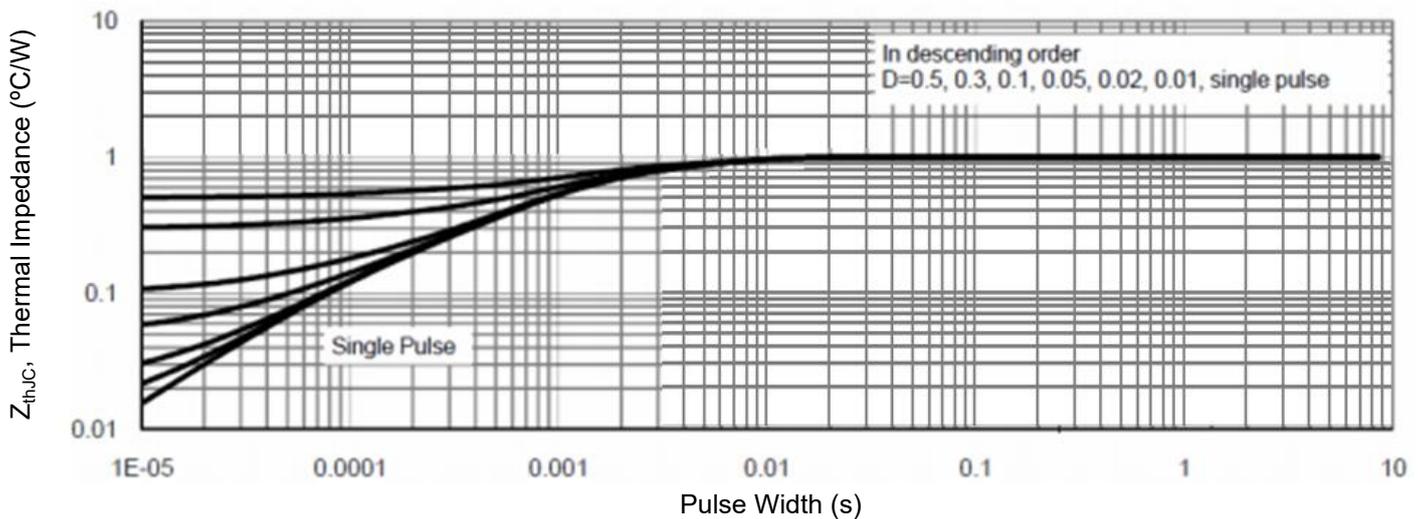
**Figure 8. Safe Operation Area**



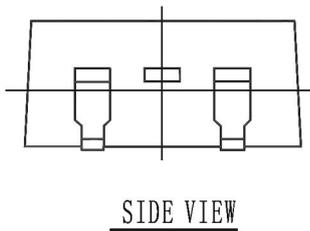
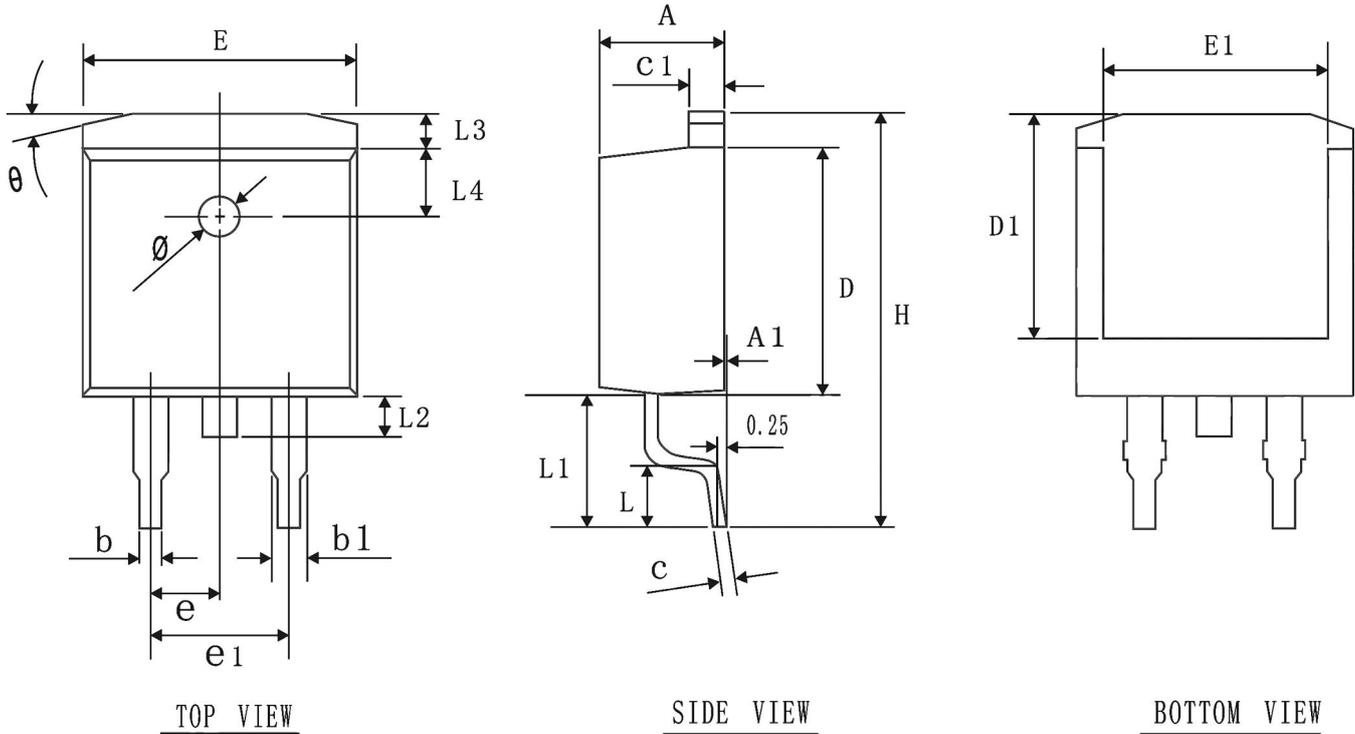
**Figure 9. Maximum Continuous Drain Current vs Case Temperature**



**Figure 10. Normalized Maximum Transient Thermal Impedance**



## TO-263 Package Information



COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	0.00	NA	0.25
b	0.70	0.80	0.90
b1	1.20	1.30	1.40
c	0.40	0.47	0.55
C1	1.25	1.30	1.35
D	9.00	9.10	9.20
D1	8.00	8.10	8.20
H	14.9	15.2	15.5
E	9.80	10.0	10.2
E1	7.85	8.00	8.15
e1	4.93	5.08	5.23
L	2.00	2.20	2.45
L1	4.60	4.80	5.00
L2	1.30	1.50	1.70
L3	1.15	1.25	1.35
L4	2.40	2.50	2.60
$\emptyset$	1.5 REF		
e	2.54 BSC		
$\theta$	13° TYP		